

### • General Description

The AGM406MNQ combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ .

This device is ideal for load switch and battery protection applications.

### • Features

- Advance high cell density Trench technology
- Low  $R_{DS(ON)}$  to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

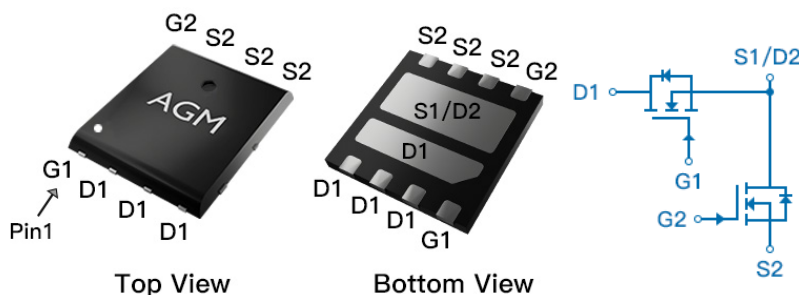
### • Application

- MB/VGA Vcore
- SMPS 2<sup>nd</sup> Synchronous Rectifier
- POL application
- BLDC Motor driver

### Product Summary

BVDSS	RDSON	ID
40V	6.5mΩ	53A

### WQFN5\*6 Pin Configuration



### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM406MNQ	AGM406MNQ	WQFN5*6	330mm	12mm	3000

**Table 1. Absolute Maximum Ratings (TA=25°C)**

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	40	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25°C) <b>(Note 1)</b>	53	A
	Drain Current-Continuous(Tc=100°C)	32	A
IDM (pluse)	Drain Current-Pulsed <b>(Note 2)</b>	212	A
PD	Maximum Power Dissipation(Tc=25°C)	28	w
	Maximum Power Dissipation(Tc=100°C)	11	w
EAS	Avalanche energy <b>(Note 3)</b>	81	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	°C

**Table 2. Thermal Characteristic**

Symbol	Parameter	Typ	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>	---	20	°C/W
RθJC	Thermal Resistance Junction-Case <sup>1</sup>	---	4.5	°C/W

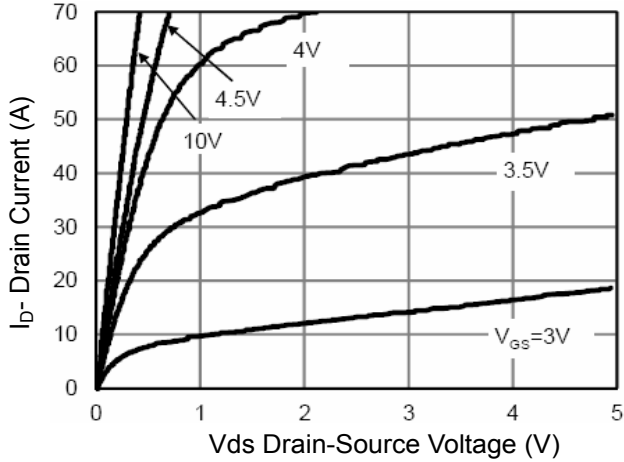
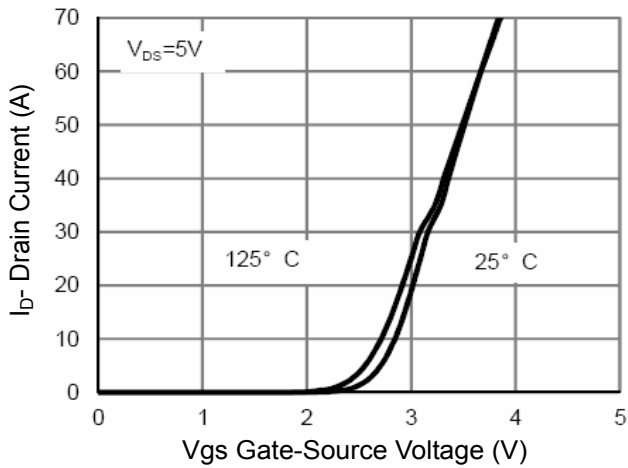
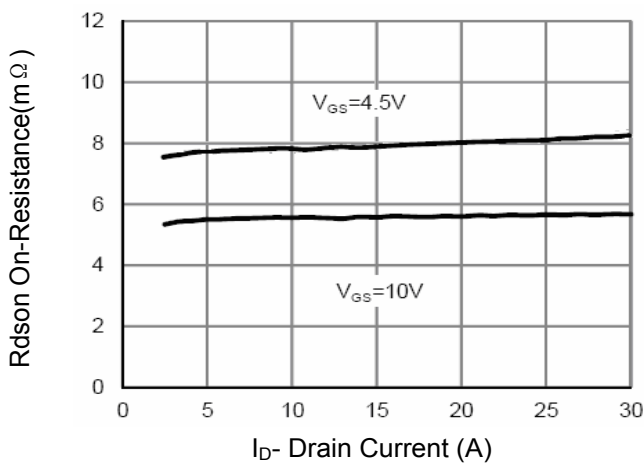
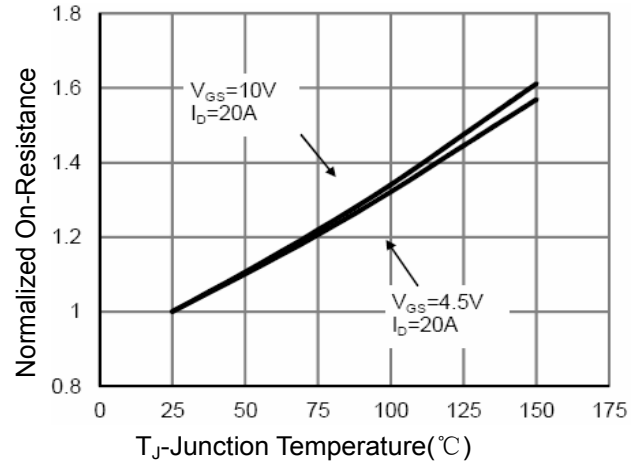
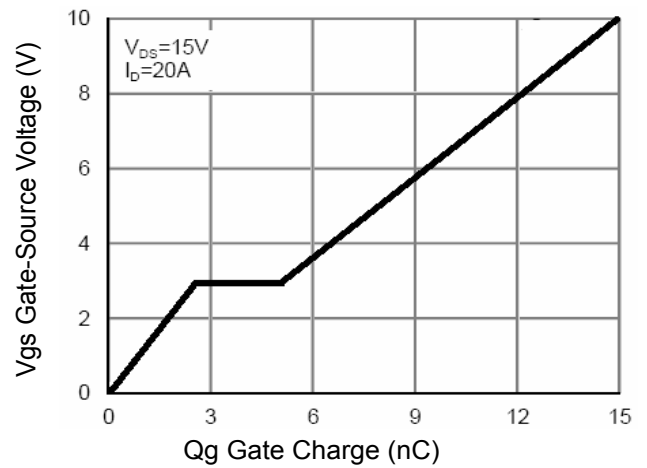
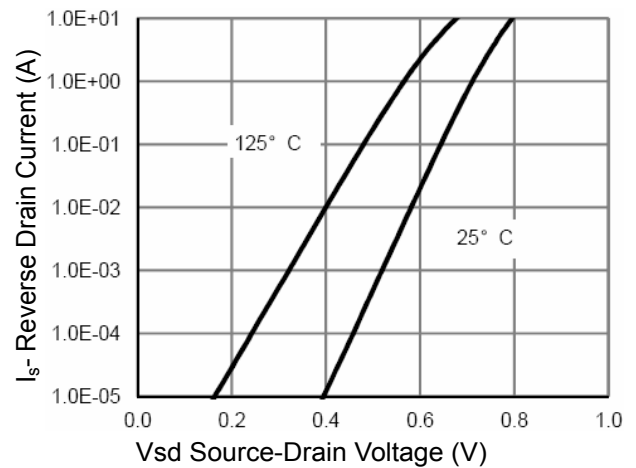
**Table 3. Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>On/Off States</b>						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	40	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=40V,VGS=0V	--	--	1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250μA	1.2	1.5	2.2	V
gFS	Forward Transconductance	VDS=5V,ID=6A	--	13	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=10A	--	6.5	9.0	mΩ
		VGS=4.5V, ID=6A	--	12	18	mΩ
<b>Dynamic Characteristics</b>						
Ciss	Input Capacitance	VDS=20V,VGS=0V, F=1MHZ	--	630	--	pF
Coss	Output Capacitance		--	160	--	pF
Crss	Reverse Transfer Capacitance		--	32	--	pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz	--	--	--	Ω
<b>Switching Times</b>						
td(on)	Turn-on Delay Time	VGS=10V,VDS=15V, RI=0.75Ω,RGEN=3.3Ω	--	6.5	--	nS
tr	Turn-on Rise Time		--	2.5	--	nS
td(off)	Turn-Off Delay Time		--	17	--	nS
tf	Turn-Off Fall Time		--	2.5	--	nS
Qg	Total Gate Charge	VGS=10V, VDS=25V, ID=12A	--	15	--	nC
Qgs	Gate-Source Charge		--	2.5	--	nC
Qgd	Gate-Drain Charge		--	2.4	--	nC
<b>Source-Drain Diode Characteristics</b>						
ISD	Source-Drain Current(Body Diode)		--	--	53	A
VSD	Forward on Voltage	VGS=0V,IS=10A	--	--	1.2	V
trr	Reverse Recovery Time	IF=10A , di/dt=100A/μs , TJ=25°C	--	--	--	ns
Qrr	Reverse Recovery Charge		--	--	--	nc

Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: T<sub>J</sub>=25°C, VDD=25V, Vgs=10V, ID=18A, L=0.5mH, RG=25ohm

**Typical Electrical and Thermal Characteristics**

**Figure 1 Output Characteristics**

**Figure 2 Transfer Characteristics**

**Figure 3 Rdson- Drain Current**

**Figure 4 Rdson-Junction Temperature**

**Figure 5 Gate Charge**

**Figure 6 Source- Drain Diode Forward**

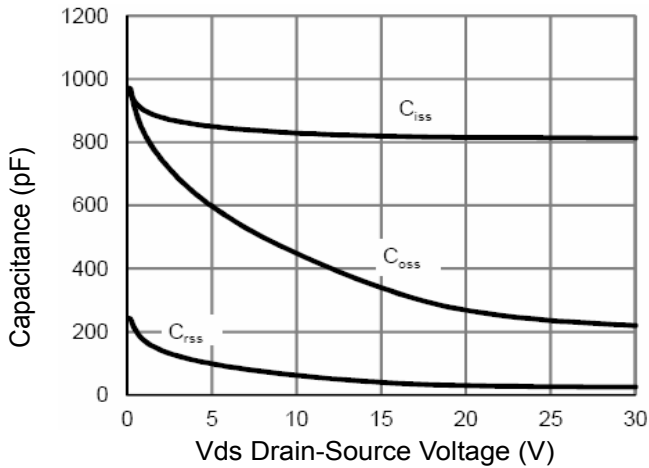


Figure 7 Capacitance vs Vds

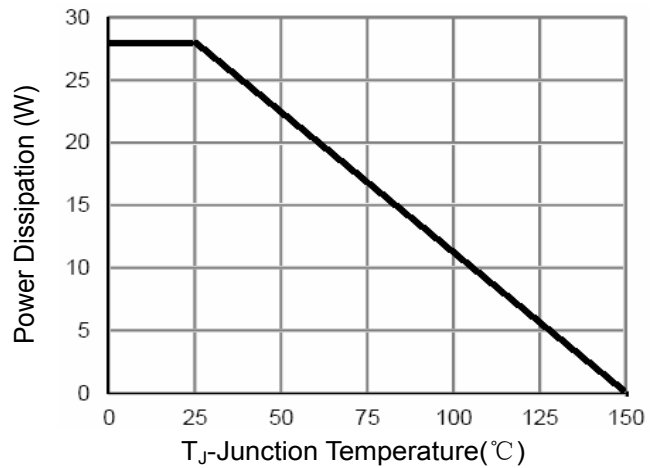


Figure 9 Power De-rating

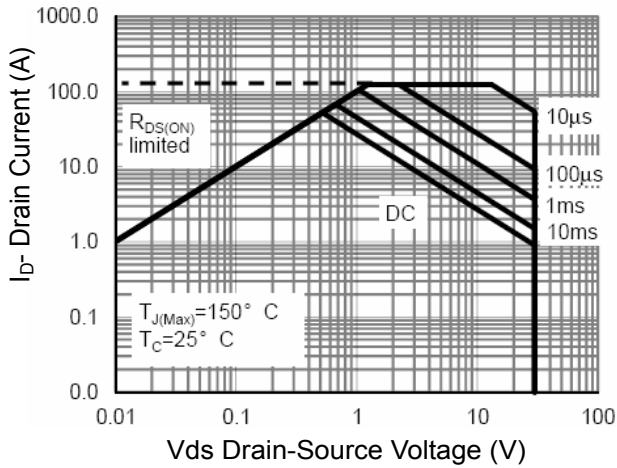


Figure 8 Safe Operation Area

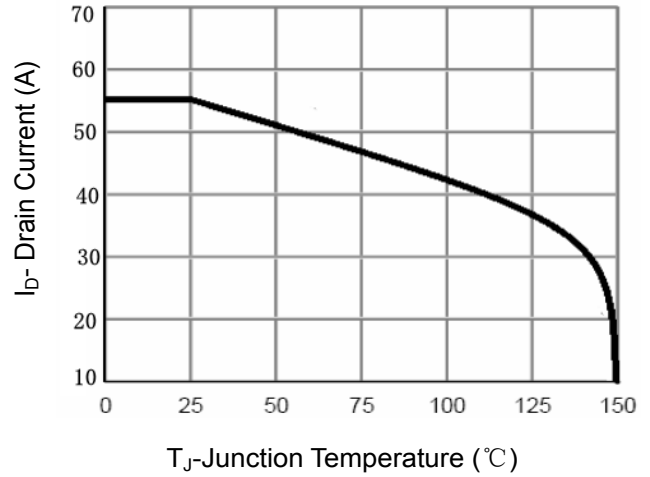


Figure 10 Current De-rating

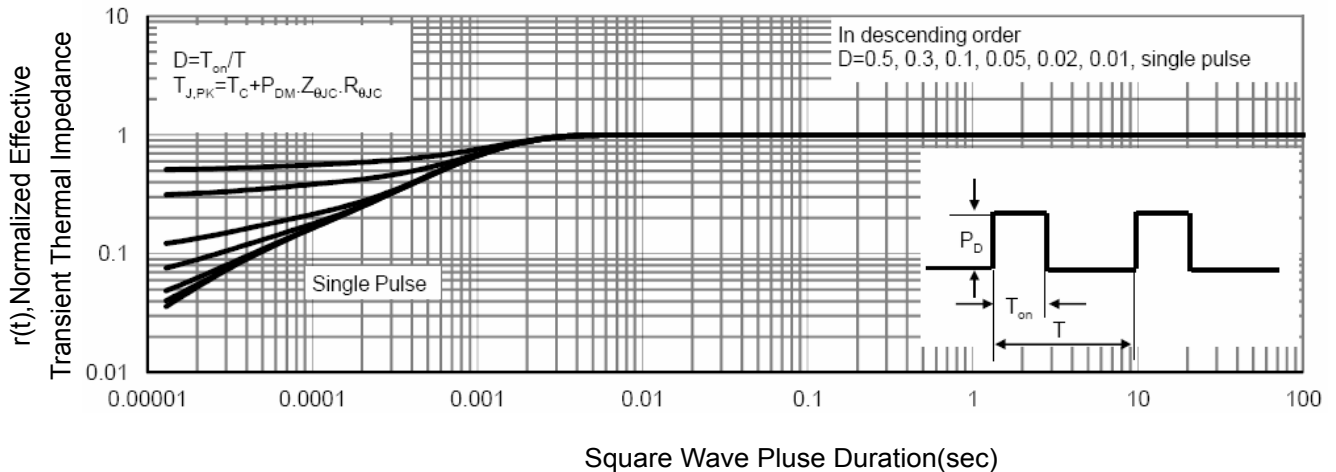
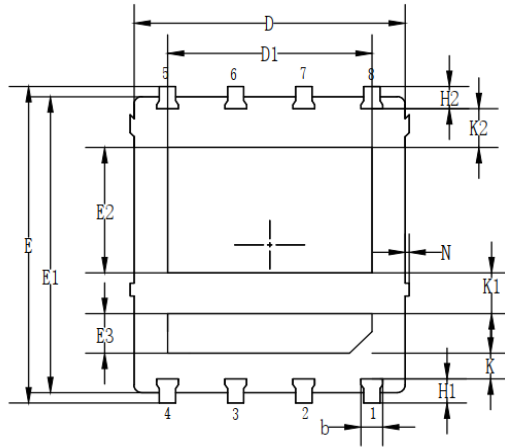
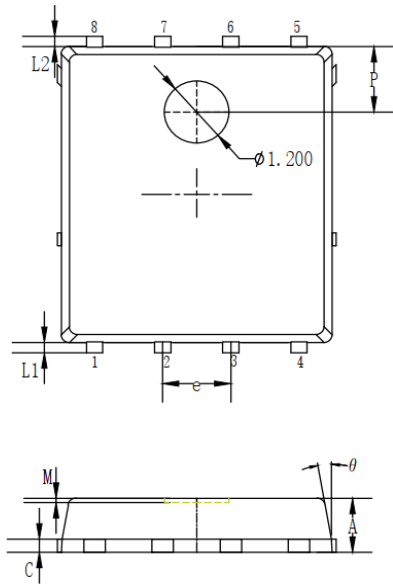
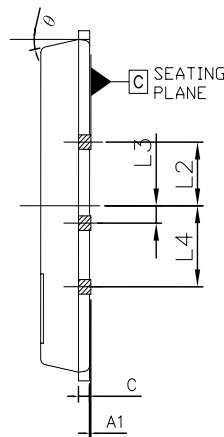
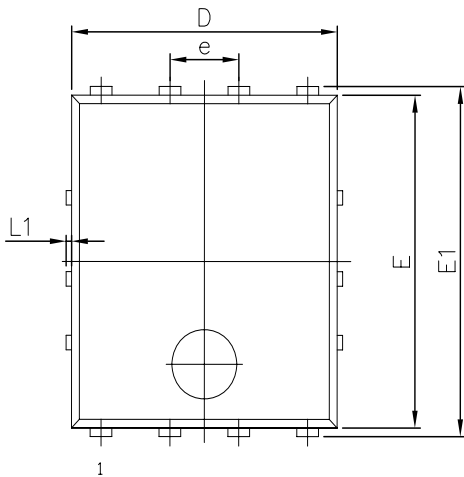


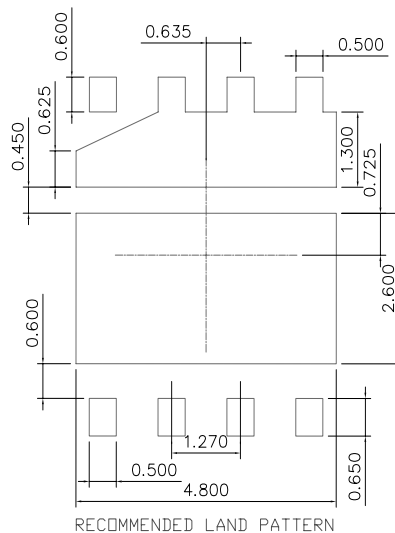
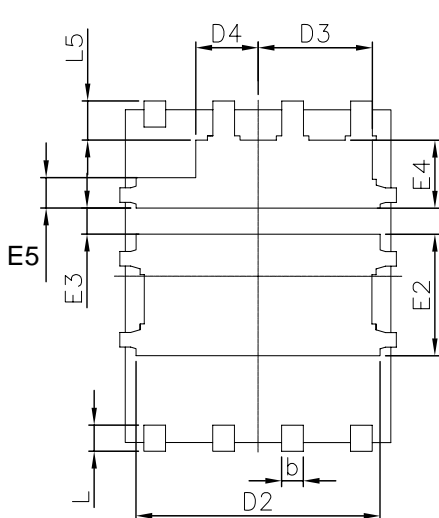
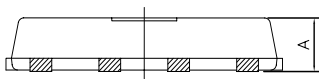
Figure 11 Normalized Maximum Transient Thermal Impedance

**WQFN5\*6 Package Outline Data**


Symbols	Millimeters		
	MIN.	NOM.	MAX.
A	0.90	1.05	1.20
b	0.35	0.40	0.50
C	0.20	0.25	0.35
D	4.90	5.05	5.20
D1	3.71	3.81	3.91
E	6.00	6.15	6.30
E1	5.65	5.75	5.85
E2	2.34	2.44	2.54
E3	0.67	0.77	0.87
e	1.27 BSC.		
H1	0.37	0.47	0.57
H2	0.33	0.43	0.53
K	0.40	0.50	0.60
K1	0.69	0.79	0.89
K2	0.65	0.75	0.85
L1/L2	0.20 REF.		
θ	8°	10°	12°
M	0.08 REF.		
N	0	-	0.15
P	1.28 REF.		



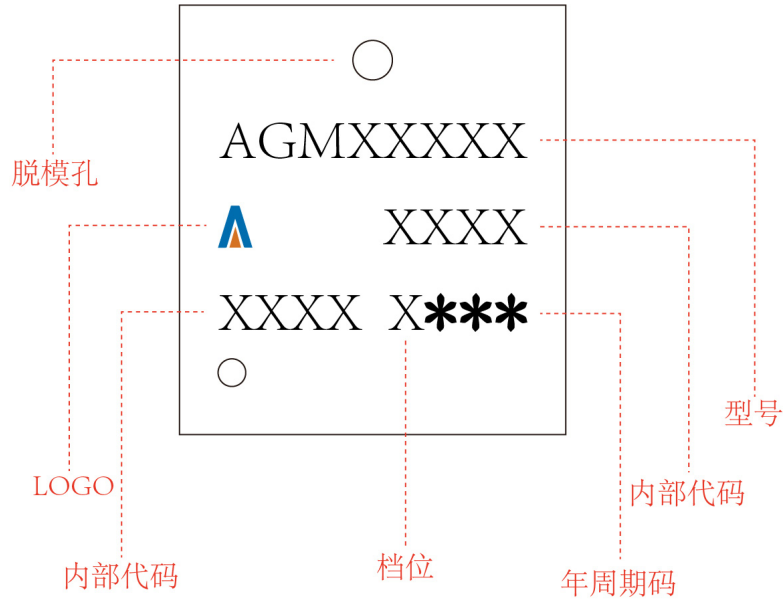
DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.85	0.90	1.00
A1	0.00	/	0.05
b	0.35	0.40	0.48
c	0.15	0.20	0.28
D	4.80	4.90	5.00
D2	4.30	4.50	4.70
D3	1.955	2.105	2.255
D4	1.000	1.150	1.300
E	5.65	5.75	5.85
E1	5.90	6.05	6.20
E2	1.95	2.10	2.25
E3	0.30	0.45	0.60
E4	1.025	1.175	1.325
E5	0.375	0.525	0.675
e	/	1.27	/
L	0.35	0.45	0.55
L1	0	/	0.15
L2	1.00	1.10	1.20
L3	0.20	0.30	0.40
L4	1.30	1.40	1.50
L5	0.575	0.675	0.775
θ	0°	12°	14°



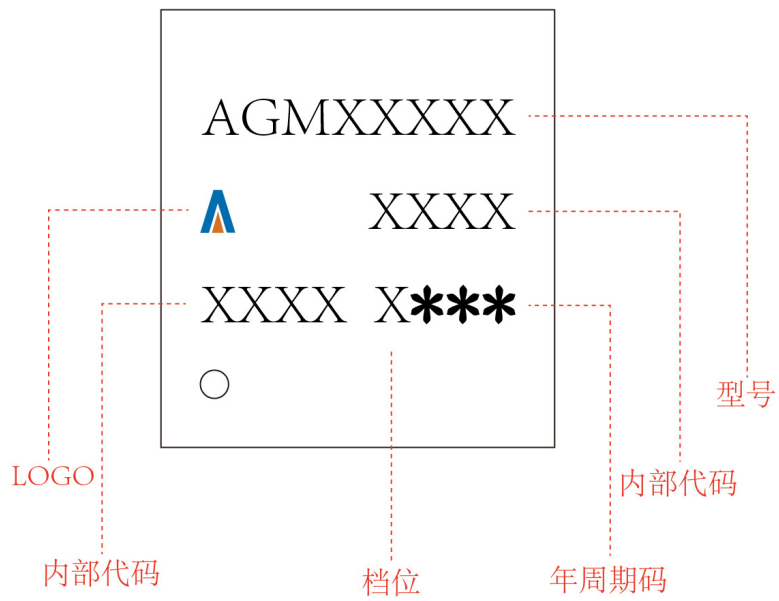
# WQFN5\*6

## Marking Instructions:

### Model1:



### Model2:




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